SBOS271 – MAY 2003

Low-Noise, High-Speed, 16-Bit Accurate, CMOS OPERATIONAL AMPLIFIER

FEATURES

- **High Bandwidth: 180MHz**
- **16-Bit Settling in 150ns**
- **Low Noise: 3nV/$\sqrt{Hz}$**
- **Low Distortion: 0.003%**
- **Low Power: 9.5mA (typ) on 5.5V**
- **Shutdown to 5μA**
- **Unity Gain Stable**
- **Excellent Output Swing: (V+) – 100mV to (V–) + 100mV**
- **Single Supply: +2.7V to +5.5V**
- **Tiny Packages: SO-8 and SOT23-6 (SOT23-6 available Q3, 2003)**

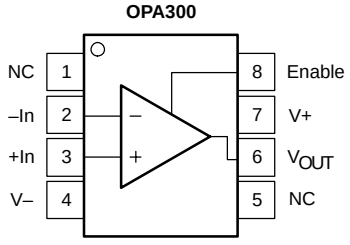
APPLICATIONS

- **16-Bit ADC Input Drivers**
- **Low-Noise Preamplifiers**
- **IF/RF Amplifiers**
- **Active Filtering**

DESCRIPTION

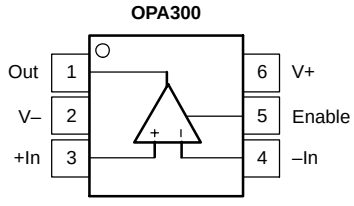
The OPA300 series high-speed, voltage-feedback, CMOS operational amplifiers are designed for 16-bit resolution systems. The OPA300 is unity gain stable and features excellent settling and harmonic distortion specifications. Low power applications benefit from the low quiescent current of the OPA300, and a digital shutdown (Enable) function provides additional power savings during idle periods. Optimized for single-supply operation, the OPA300 offers superior output swing and excellent common-mode range.

The OPA300 has 180MHz of unity gain bandwidth, 500MHz of available bandwidth, low 3nV/$\sqrt{Hz}$ voltage noise, and 0.1% settling within 30ns. Single-supply operation on 2.7V (±1.35V) and 5.5V (±2.75V) and a shutdown function that reduces supply current to 5μA are useful for portable low-power applications. The OPA300 is available in SO-8 packages, with SOT23-6 packages to be available Q3, 2003. The OPA300 is specified over the industrial temperature range of –40°C to +125°C.



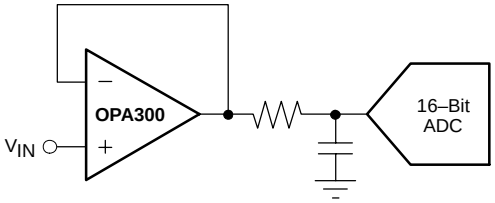
SO-8

NC = Not Connected



SOT23-6(1)

(1) Available Q3, 2003



Typical Application of the OPA300

PACKAGE/ORDERING INFORMATION

PRODUCT	PACKAGE–LEAD	PACKAGE DESIGNATOR(1)	SPECIFIED TEMPERATURE RANGE	PACKAGE MARKING	ORDERING NUMBER	TRANSPORT MEDIA, QUANTITY
OPA300D	SO–8	D	–40°C to +125°C	300A	OPA300AID	Tube, 100
					OPA300AIDR	Tape and Reel, 2500
OPA300DBV(2)	SOT23-6	DBV	–40°C to +125°C	A52	OPA300AIDBVT	Tape and Reel, 250
					OPA300AIDBVR	Tape and Reel, 2500

(1) For the most current specification and package information, refer to our web site at www.ti.com.
(2) Shaded area indicates availability Q3, 2003.

ABSOLUTE MAXIMUM RATINGS

over operating free-air temperature range unless otherwise noted(1)

Power Supply V+	5.5V
Signal Input Terminals(2), Voltage	0.5V to (V+) + 0.5V
Current	±10mA
Open Short-Circuit Current(3)	Continuous
Operating Temperature Range	–55°C to +125°C
Storage Temperature Range	–60°C to +150°C
Junction Temperature	+150°C
Lead Temperature (soldering, 10s)	+300°C

(1) Stresses above these ratings may cause permanent damage. Exposure to absolute maximum conditions for extended periods may degrade device reliability. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those specified is not implied.

(2) Input terminals are diode clamped to the power-supply rails. Input signals that can swing more than 0.5V beyond the supply rails should be current limited to 10mA or less.

(3) Short-circuit to ground; one amplifier per package.

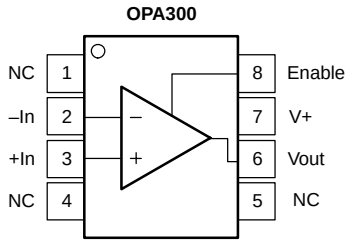
ELECTROSTATIC DISCHARGE SENSITIVITY

This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

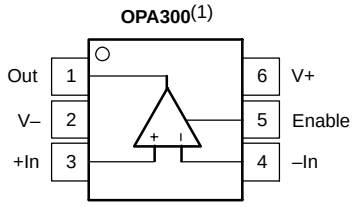
PIN ASSIGNMENTS

TOP VIEW — SO



NC = Not Connected

TOP VIEW — SOT23



(1) Available Q3, 2003

ELECTRICAL CHARACTERISTICS: V_S = 2.7V TO 5.5V

Boldface limits apply over the temperature range, T_A = –40°C to +125°C.

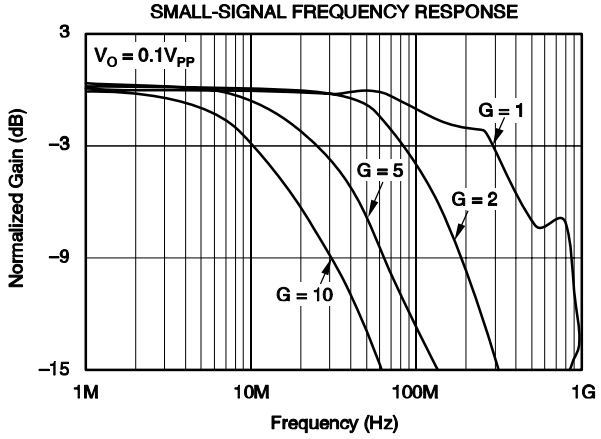
All specifications at T_A = +25°C, R_L = 2kΩ connected to V_S/2, V_{OUT} = V_S/2, and V_{CM} = V_S/2, unless otherwise noted.

PARAMETER		TEST CONDITIONS	OPA300 MIN	OPA300 TYP	OPA300 MAX	UNITS
OFFSET VOLTAGE						
Input Offset Voltage	V_{OS}	V_S = 5V		1	5	mV
Over Temperature					**7**	**mV**
Drift	**dV_{OS}/dT**			**2.5**		**µV/°C**
vs. Power Supply	**PSRR**	**V_S = 2.7V to 5.5V, V_{CM} < (V+) –0.9V**		**50**	**200**	**µV/V**
INPUT VOLTAGE RANGE						
Common–Mode Voltage Range	V_{CM}		(V–) – 0.2		(V+) – 0.9	V
Common–Mode Rejection Ratio	**CMRR**	**(V–) – 0.2V < V_{CM} < (V+) – 0.9V**	**66**	**80**		**dB**
INPUT BIAS CURRENT						
Input Bias Current	I_B			±0.1	±5	pA
Input Offset Current	I_{OS}			±0.5	±5	pA
INPUT IMPEDANCE						
Differential				10^{13} || 3		Ω || pF
Common–Mode				10^{13} || 6		Ω || pF
NOISE						
Input Voltage Noise, f = 0.1Hz to 1MHz				40		µVpp
Input Voltage Noise Density, f = 100kHz	e_n			3		nV/√Hz
Input Current Noise Density, f = 1kHz	i_n			1.5		fA/√Hz
Differential Gain Error		R_L = 150Ω		0.01		%
Differential Phase Error		R_L = 150Ω		0.1		°
OPEN–LOOP GAIN						
Open–Loop Voltage Gain	A_{OL}	V_S = 5V, R_L = 2kΩ, 0.1V < V_O < 4.9V	95	106		dB
Over Temperature		**V_S = 5V, R_L = 2k , 0.1V < V_O < 4.9V**	**90**			**dB**
		V_S = 5V, R_L = 100Ω, 0.5V < V_O < 4.5V	95	106		dB
Over Temperature		**V_S = 5V, R_L = 100 , 0.5V < V_O < 4.5V**	**90**			**dB**
OUTPUT						
Voltage Output Swing from Rail		R_L = 2kΩ, A_{OL} > 95dB		75	100	mV
		R_L = 100Ω, A_{OL} > 95dB		300	500	mV
Short–Circuit Current	I_{SC}			70		mA
Capacitive Load Drive	C_{LOAD}			See Typical Characteristic		
FREQUENCY RESPONSE						
Gain–Bandwidth Product	GBW			180		MHz
Slew Rate	SR	G = +1		80		V/µs
Settling Time, 0.01%	t_S	V_S = 5V, 2V Step, G = +1		90		ns
0.1%				30		ns
Overload Recovery Time		Gain = –1		30		ns
Total Harmonic Distortion + Noise	THD+N	V_S = 5V, V_O = 3Vpp, G = +1, f = 1kHz		0.003		%
POWER SUPPLY						
Specified Voltage Range	V_S		2.7		5.5	V
Operating Voltage Range				2.7 to 5.5		V
Quiescent Current (per amplifier)	I_Q	I_O = 0		9.5	12	mA
Over Temperature					**13**	**mA**
SHUTDOWN						
t_{OFF}				40		ns
t_{ON}				5		µs
V_L (shutdown)			(V–) – 0.2		(V–) + 0.8	V
V_H (amplifier is active)			(V–) + 2.5		(V+) + 0.2	V
I_{QSD}				3	5	µA
TEMPERATURE RANGE						
Specified Range			–40		125	°C
Operating Range			–55		150	°C
Storage Range			–65		150	°C
Thermal Resistance	θ_{JA}					°C/W
SO–8				200		°C/W

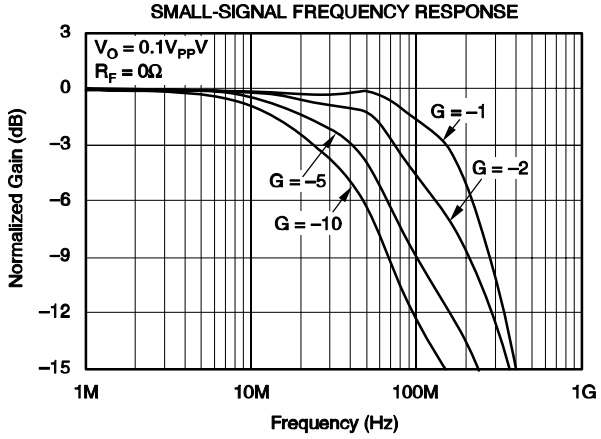
TYPICAL CHARACTERISTICS

All specifications at T_A = 25°C, V+ = 5V, R_F = 310Ω, and R_L = 150Ω connected to V_S/2 unless otherwise noted.

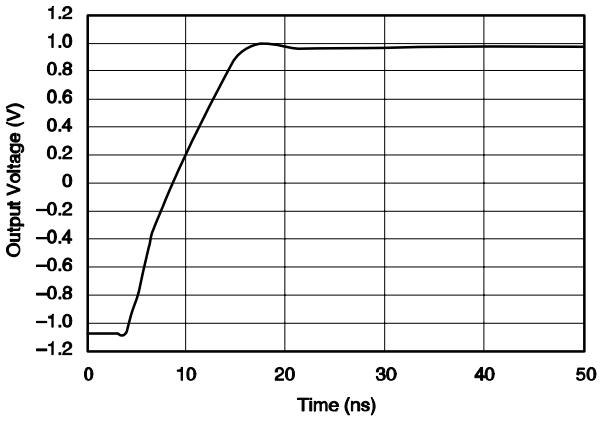
NONINVERTING GAIN
SMALL-SIGNAL FREQUENCY RESPONSE



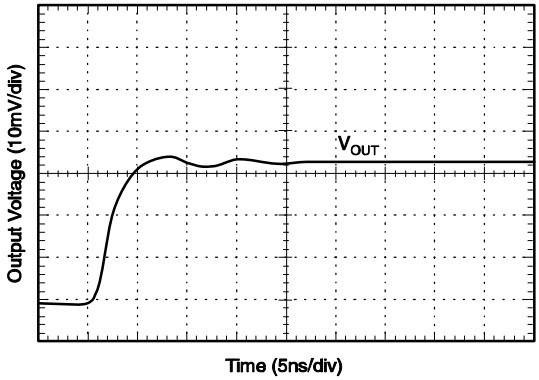
INVERTING GAIN
SMALL-SIGNAL FREQUENCY RESPONSE



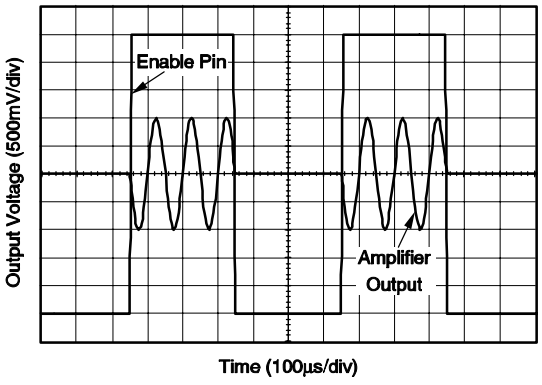
LARGE-SIGNAL STEP RESPONSE



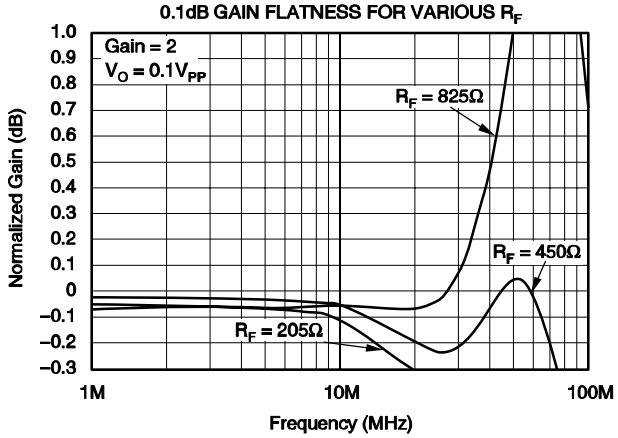
SMALL-SIGNAL STEP RESPONSE



LARGE-SIGNAL ENABLE/DISABLE RESPONSE



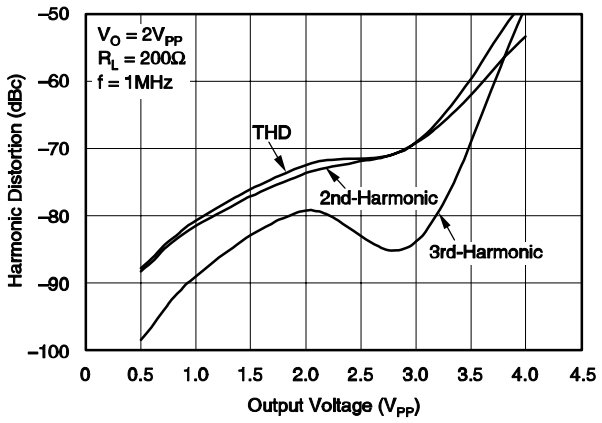
0.1dB GAIN FLATNESS FOR VARIOUS R_F



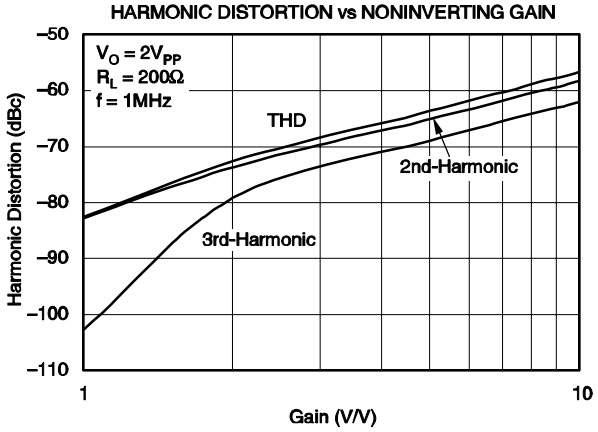
TYPICAL CHARACTERISTICS (continued)

All specifications at T_A = 25°C, V+ = 5V, R_F = 310Ω, and R_L = 150Ω connected to V_S/2 unless otherwise noted.

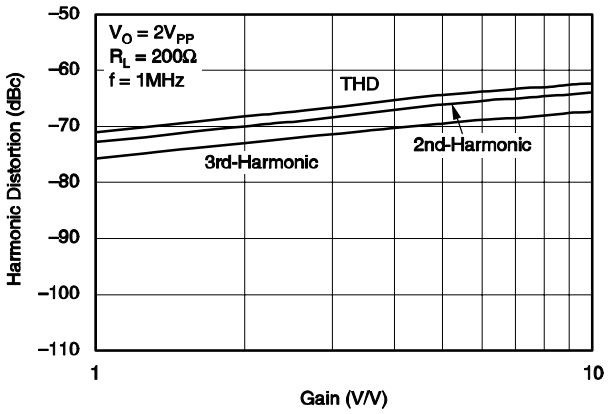
HARMONIC DISTORTION vs OUTPUT VOLTAGE



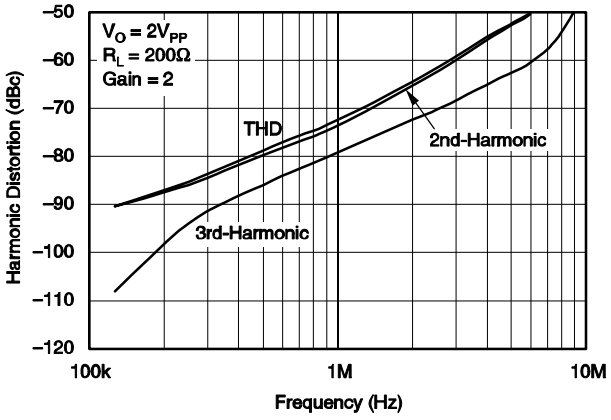
HARMONIC DISTORTION vs NONINVERTING GAIN



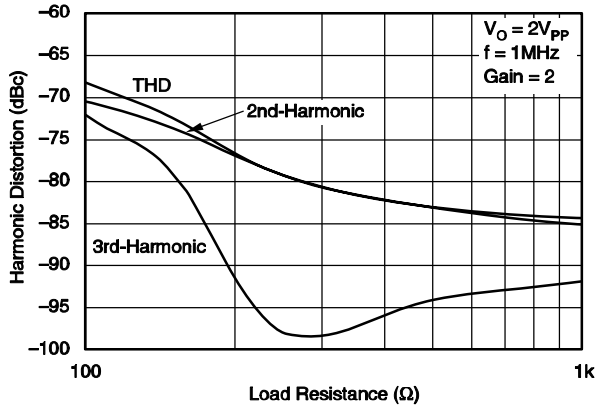
HARMONIC DISTORTION vs INVERTING GAIN



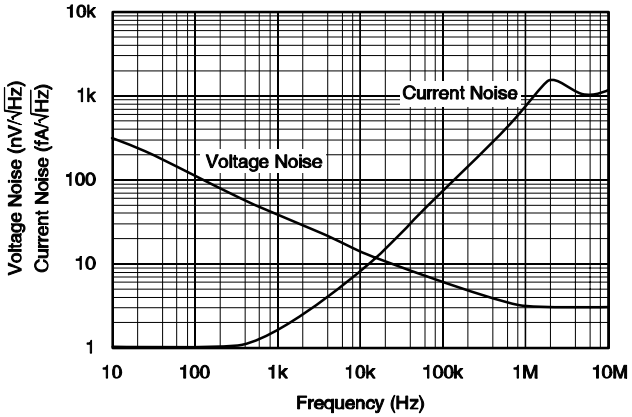
HARMONIC DISTORTION vs FREQUENCY



HARMONIC DISTORTION vs LOAD RESISTANCE



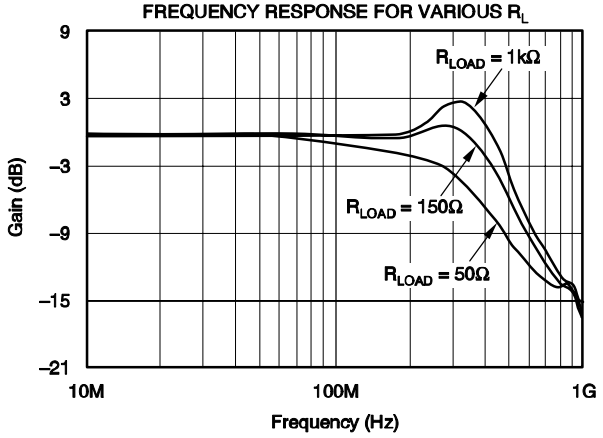
INPUT VOLTAGE AND CURRENT NOISE SPECTRAL DENSITY vs FREQUENCY



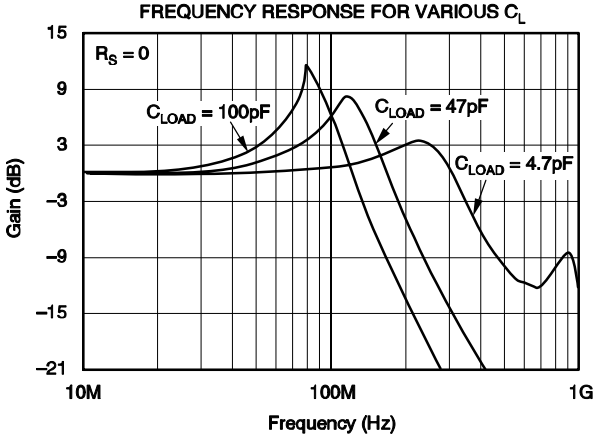
TYPICAL CHARACTERISTICS (continued)

All specifications at T_A = 25°C, V+ = 5V, R_F = 310Ω, and R_L = 150Ω connected to V_S/2 unless otherwise noted.

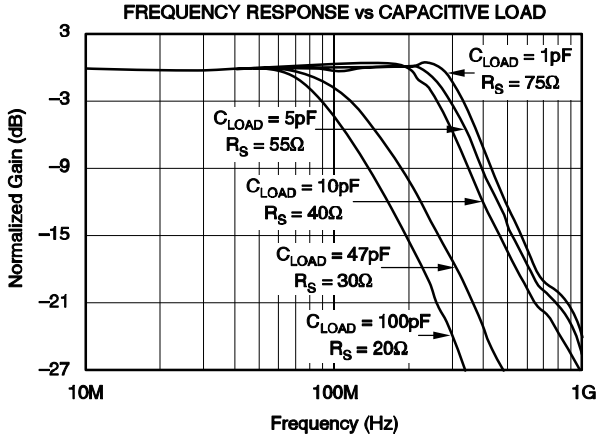
FREQUENCY RESPONSE FOR VARIOUS R_L



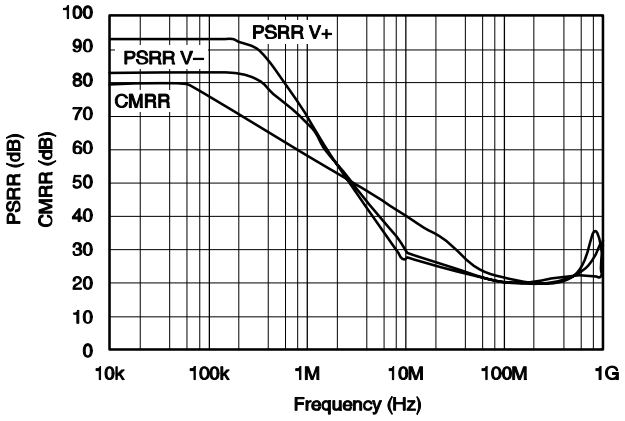
FREQUENCY RESPONSE FOR VARIOUS C_L



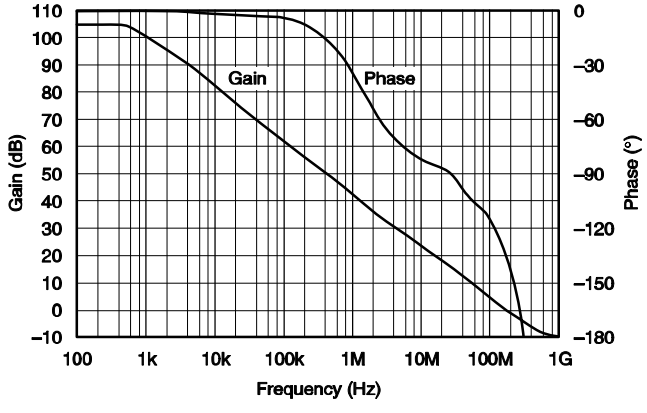
FREQUENCY RESPONSE vs CAPACITIVE LOAD



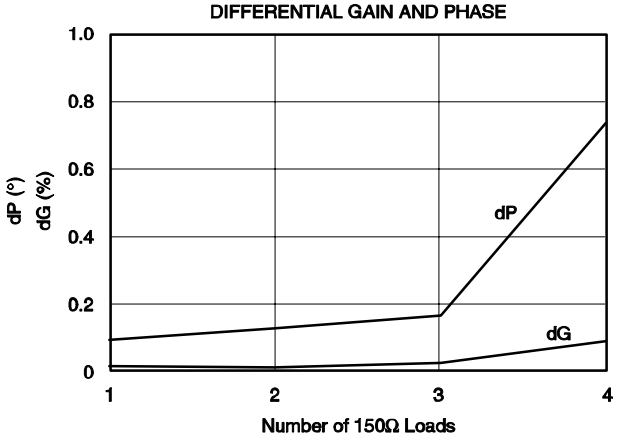
COMMON-MODE REJECTION RATIO AND POWER-SUPPLY REJECTION RATIO vs FREQUENCY



OPEN-LOOP GAIN AND PHASE vs FREQUENCY



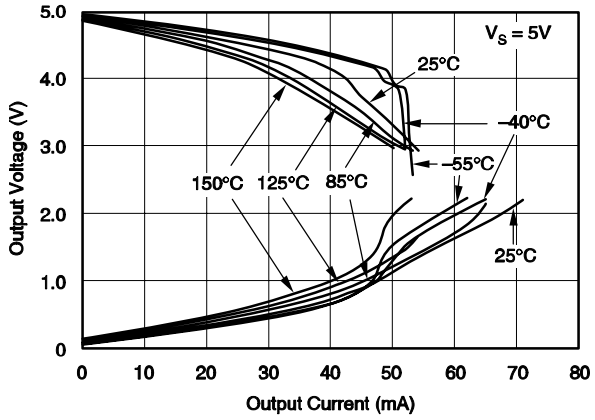
COMPOSITE VIDEO DIFFERENTIAL GAIN AND PHASE



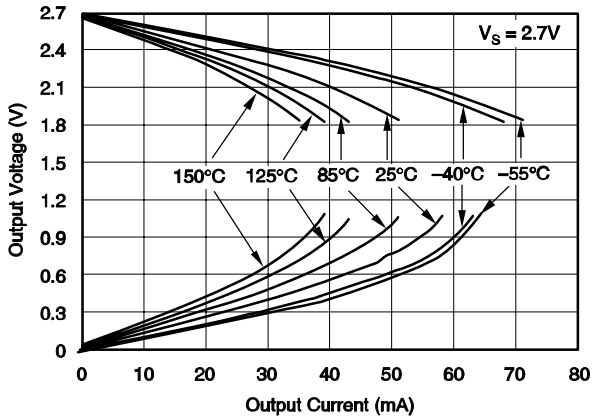
TYPICAL CHARACTERISTICS (continued)

All specifications at T_A = 25°C, V+ = 5V, R_F = 310Ω, and R_L = 150Ω connected to V_S/2 unless otherwise noted.

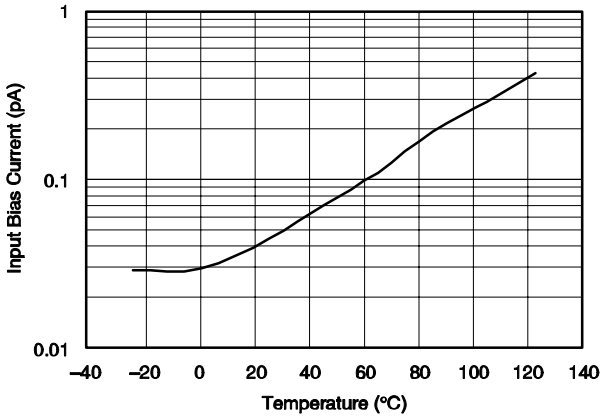
OUTPUT VOLTAGE SWING vs OUTPUT CURRENT



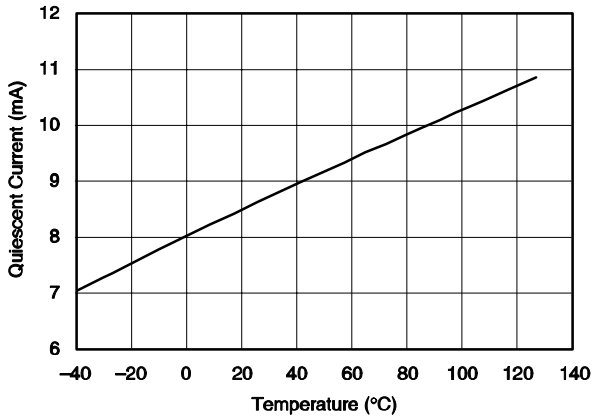
OUTPUT VOLTAGE SWING vs OUTPUT CURRENT



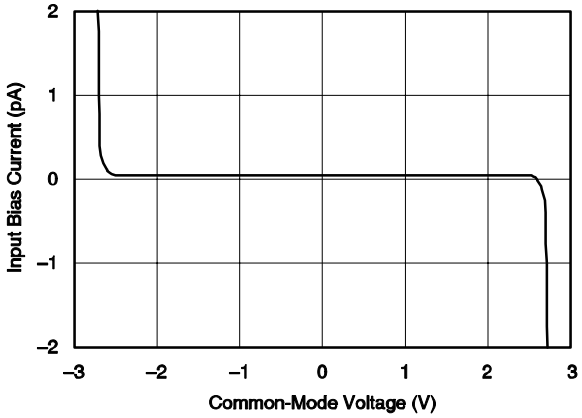
INPUT BIAS CURRENT vs TEMPERATURE



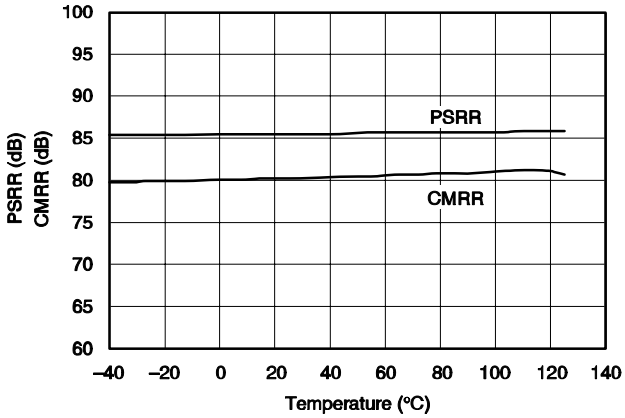
QUIESCENT CURRENT vs TEMPERATURE



INPUT BIAS CURRENT vs COMMON-MODE VOLTAGE



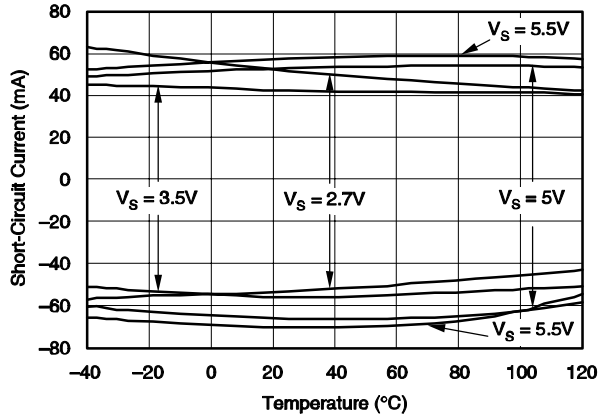
POWER-SUPPLY REJECTION RATIO AND
COMMON-MODE REJECTION RATIO vs TEMPERATURE



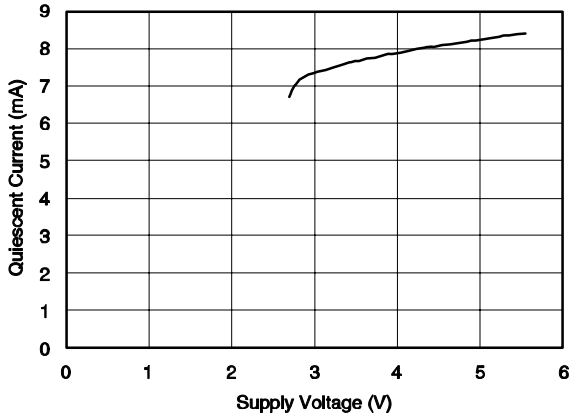
TYPICAL CHARACTERISTICS (continued)

All specifications at T_A = 25°C, V+ = 5V, R_F = 310Ω, and R_L = 150Ω connected to V_S/2 unless otherwise noted.

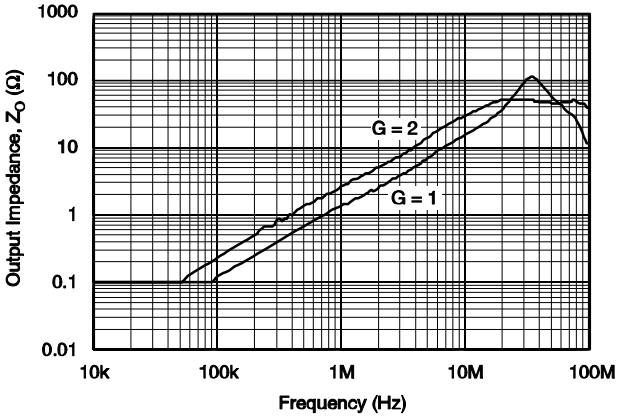
SHORT-CIRCUIT CURRENT vs TEMPERATURE



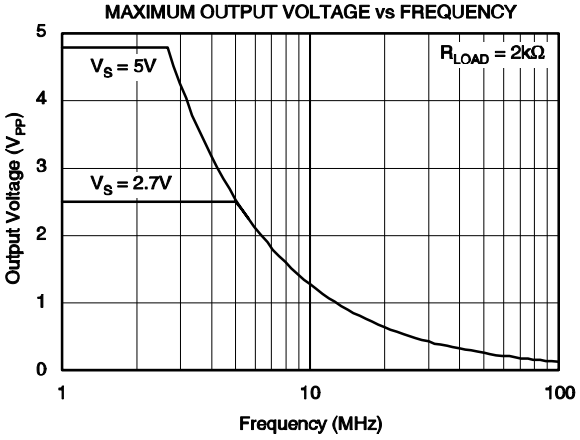
QUIESCENT CURRENT vs SUPPLY VOLTAGE



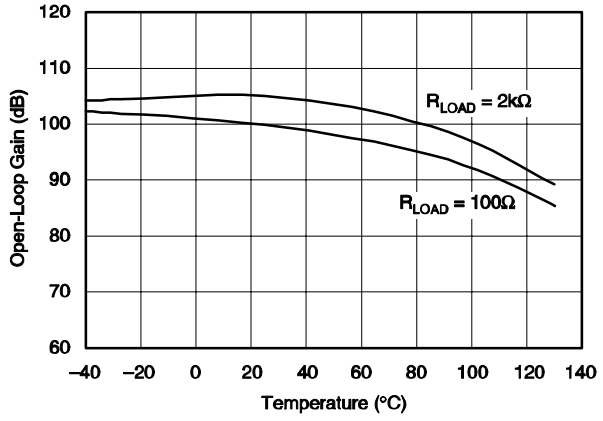
OUTPUT IMPEDANCE vs FREQUENCY



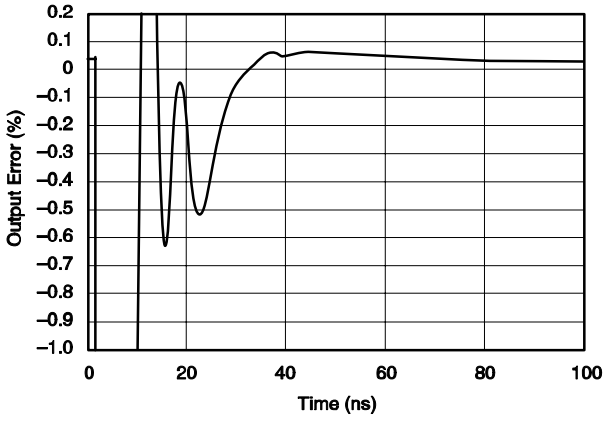
MAXIMUM OUTPUT VOLTAGE vs FREQUENCY



OPEN-LOOP GAIN vs TEMPERATURE

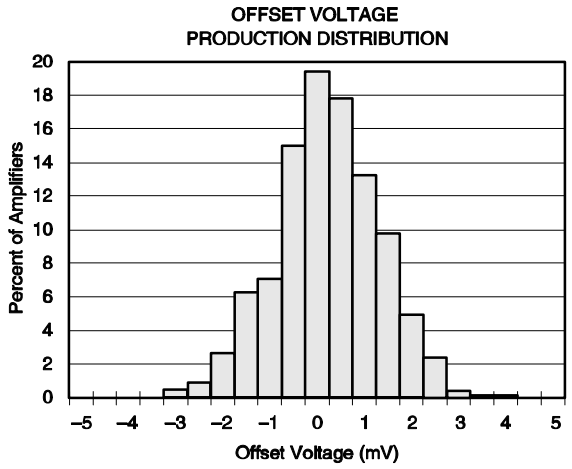


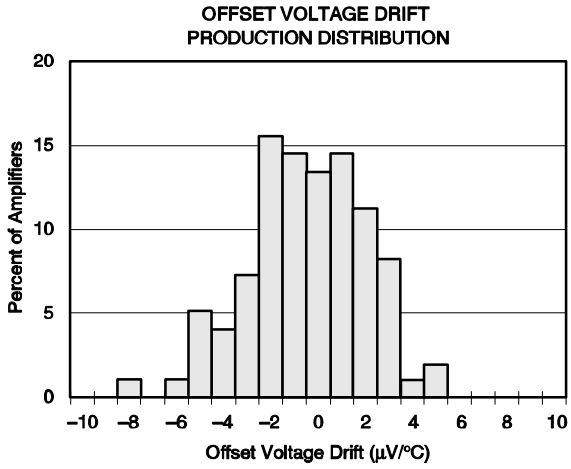
OUTPUT SETTLING TIME TO 0.1%



TYPICAL CHARACTERISTICS (continued)

All specifications at T_A = 25°C, V+ = 5V, R_F = 310Ω, and R_L = 150Ω connected to V_S/2 unless otherwise noted.





APPLICATIONS INFORMATION

Built on HPA07, the latest TI high-precision analog process, the OPA300 single-supply CMOS op amp is designed to interface with high-speed 16-bit analog-to-digital converters (ADCs). Featuring wide 180MHz bandwidth, fast 150nS settling time to 16 bits, and high open loop gain, the OPA300 series offer excellent performance in a small SO-8 package.

THEORY OF OPERATION

The OPA300 uses a classic two-stage topology, shown in Figure 1. The differential input pair is biased to maximize slew rate without compromising stability or bandwidth. The folded cascode adds the signal from the input pair and presents a differential signal to the class AB output stage. The class AB output stage allows rail to rail output swing, with high–impedance loads (> 2kΩ), typically 100mV from the supply rails. With 10Ω loads, a useful output swing can be achieved and still maintain high open-loop gain. See the typical characteristic *Output Voltage Swing vs Output Current.*

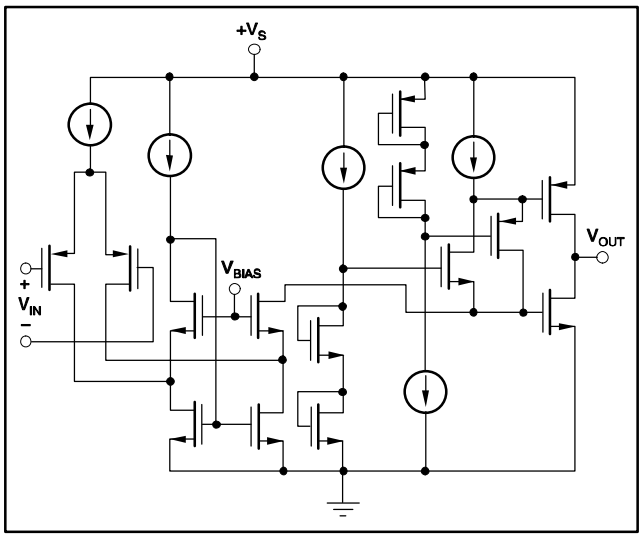


Figure 1. OPA300 Classic Two-Stage Topology

OPERATING VOLTAGE

OPA300 op amp parameters are fully specified from +2.7V to +5.5V. Supply voltages higher than 5.5V (absolute maximum) can cause permanent damage to the amplifier. Many specifications apply from –40°C to +125°C. Parameters that vary significantly with operating voltages or temperature are shown in the Typical Characteristics.

PCB LAYOUT

As with most high-speed operational amplifiers, board layout requires special attention to maximize AC and DC performance. Extensive use of ground planes, short lead lengths, and high-quality bypass capacitors will minimize leakage that can compromise signal quality. Guard rings applied with potential as near to the input pins as possible help minimize board leakage.

INPUT AND ESD PROTECTION

All OPA300 pins are static protected with internal ESD protection diodes tied to the supplies, as shown in Figure 2. These diodes will provide overdrive protection if the current is externally limited to 10mA, as stated in the Absolute Maximum Ratings. Any input current beyond the Absolute Maximum Ratings, or long-term operation at maximum ratings, will shorten the lifespan of the amplifier.

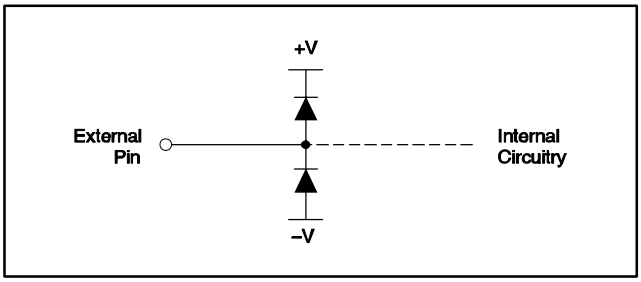


Figure 2. ESD Protection Diodes

ENABLE FUNCTION

The shutdown function of the OPA300 is referenced to the negative supply voltage of the operational amplifier. A logic level HIGH enables the op amp. A valid logic HIGH is defined as 2.5V above the negative supply applied to the enable pin. A valid logic LOW is defined as < 0.8V above the negative supply pin. If dual or split power supplies are used, care should be taken to ensure logic input signals are properly referred to the negative supply voltage. If this pin is not connected to a valid high ot low voltage, the internal circuitry will pull the node high and enable the part to function.

The logic input is a high-impedance CMOS input. For battery-operated applications, this feature may be used to greatly reduce the average current and extend battery life. The enable time is 10μs; disable time is 1μs. When disabled, the output assumes a high-impedance state. This allows the OPA300 to be operated as a gated amplifier, or to have its output multiplexed onto a common analog output bus.

DRIVING CAPACITIVE LOADS

When using high–speed operational amplifiers, it is extremely important to consider the effects of capacitive loading on amplifier stability. Capacitive loading will interact with the output impedance of the operational amplifier, and depending on the capacitor value, may significantly decrease the gain bandwidth, as well as introduce peaking. To reduce the effects of capacitive loading and allow for additional capacitive load drive, place a series resistor between the output and the load. This will reduce available bandwidth, but permit stable operation with capacitive loading. Figure 3 illustrates the recommended relationship between the resistor and capacitor values.

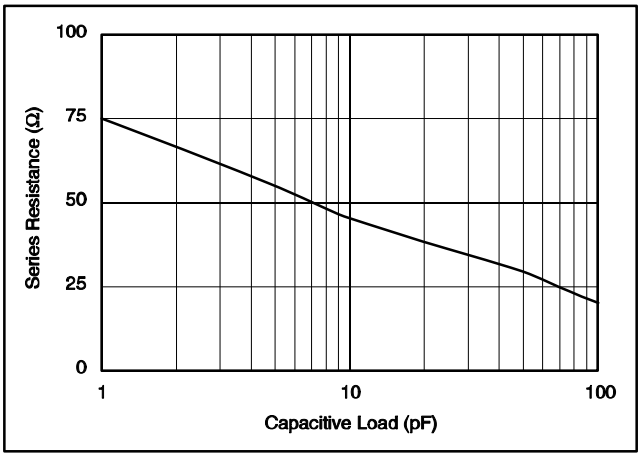


Figure 3. Recommended R_S and C_L Combinations

Amplifiers configured in unity gain are most susceptible to stability issues. The typical characteristic, *Frequency Response vs Capacitive Load,* describes the relationship between capacitive load and stability for the OPA300. In unity gain, the OPA300 is capable of driving a few picofarads of capacitive load without compromising stability. Board level parasitic capacitance can often fall into the range of a picofarad or more, and should be minimized through good circuit-board layout practices to avoid compromising the stability of the OPA300.

DRIVING A 16-BIT ADC

The OPA300 features excellent THD+noise, even at frequencies greater than 1MHz, with a 16-bit settling time of 150ns. Figure 4 shows a total single supply solution for high-speed data acquisition. The OPA300 directly drives the ADS8401, a 1.25 mega sample per second (MSPS) 16-bit data converter. The OPA300 is configured in an inverting gain of 1, with a 5V single supply. Results of the OPA300 performance are summarized in Table 1.

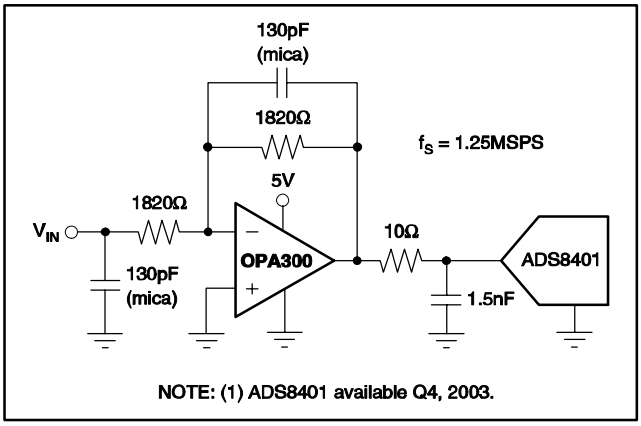


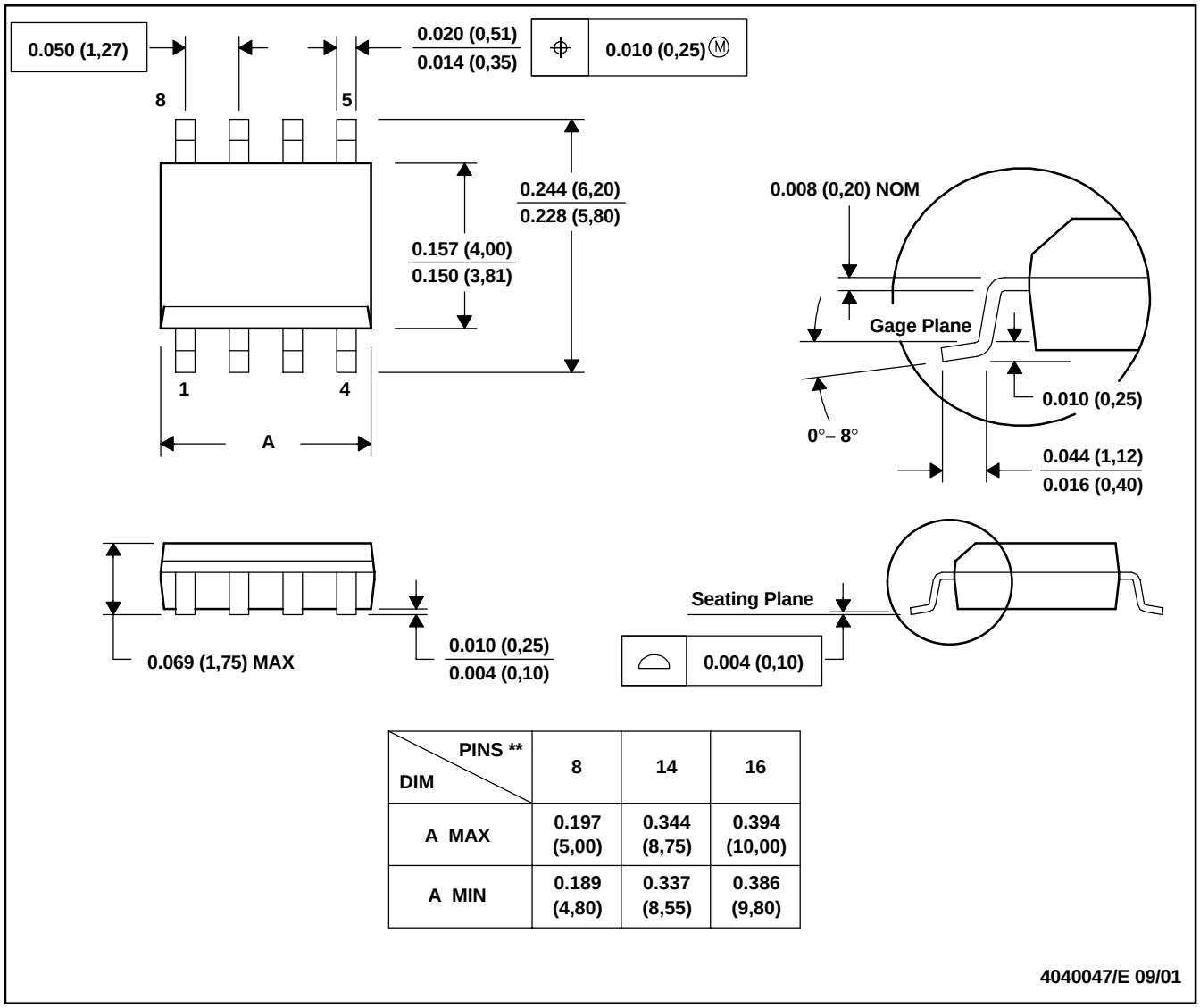
Figure 4. The OPA300 Drives the 16-Bit ADS8401

PARAMETER	RESULTS
THD+Noise	99.3dB
SFDR	101.3dB
2nd Harmonic	107.4dB
3rd Harmonic	103.5dB

Table 1. OPA300 Performance Results Driving a 1.25MSPS ADS8401

D (R-PDSO-G**) PLASTIC SMALL-OUTLINE PACKAGE

8 PINS SHOWN



DIM \ PINS **	8	14	16
A MAX	0.197 (5,00)	0.344 (8,75)	0.394 (10,00)
A MIN	0.189 (4,80)	0.337 (8,55)	0.386 (9,80)

4040047/E 09/01

NOTES:A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion, not to exceed 0.006 (0,15).
D. Falls within JEDEC MS-012

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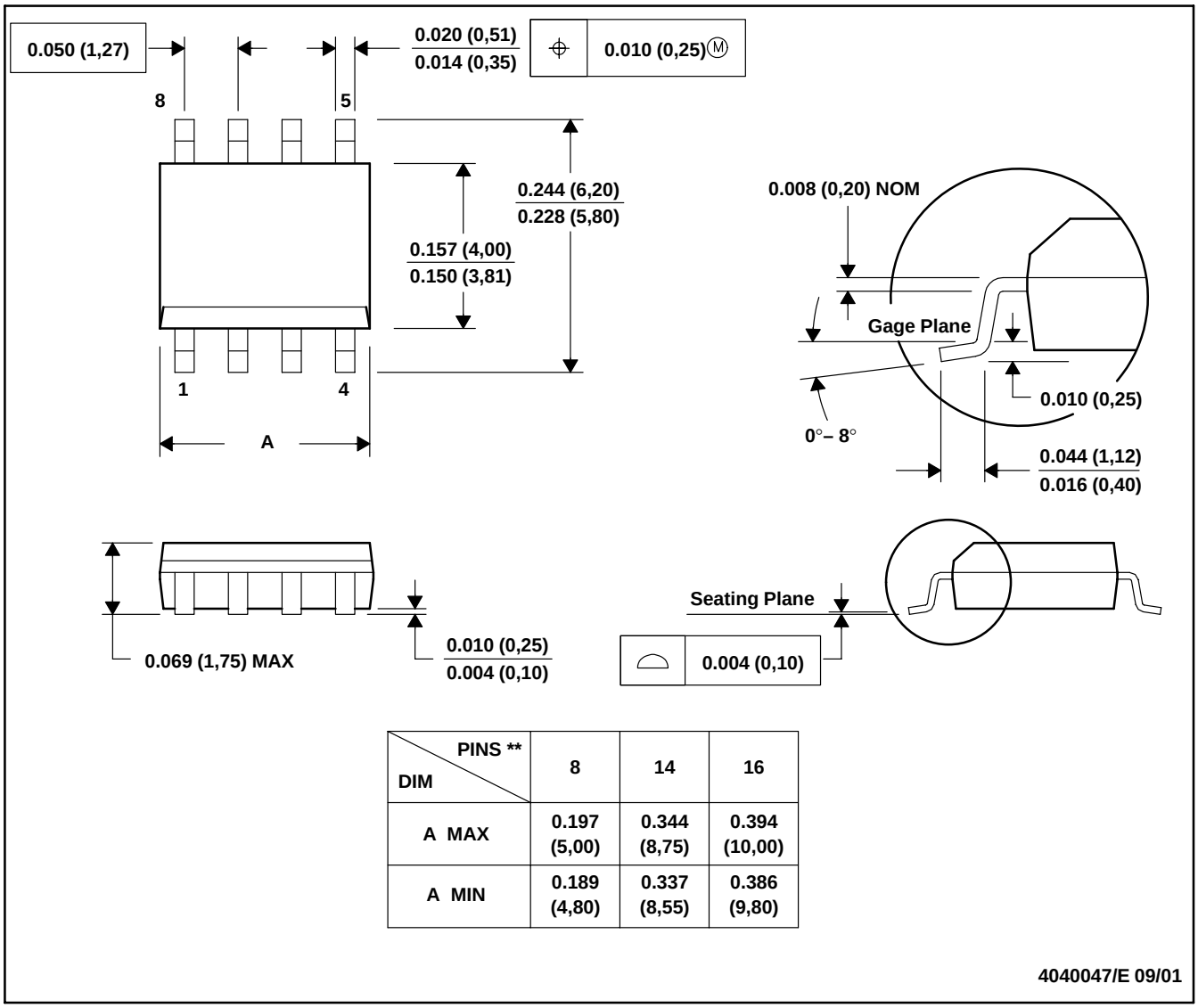
D (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

8 PINS SHOWN



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